

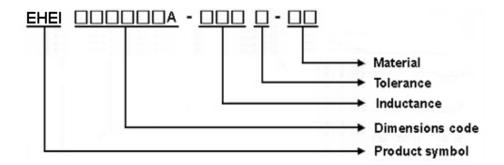
ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

RoHS & Halogen Free & REACH Compliance.

SPECIFICATION FOR APPROVAL

Customer:	超利維							
Customer P/N:								
Drawing No:		IE1-8B0364						
Quantity:	X	Pcs.	DATE:	2018/11/16				
Chilisin P/N:		EHEI252010A-1R0M-Q8						
	SPE	CIFIC	ATION					
	AC	CEPTE	D BY:					
COMPONENT								
ENGINEER								
ELECTRICAL								
ENGINEER								
MECHANICAL								
ENGINEER								
APPROVED								
REJECTED								
奇力新電子股份有限公司 Chillisin Electronics Corp No. 29, Alley 301, Tehhsin Rd., Hukou, Hsinchu 303, Taiwan TEL: +886-3-599-2646 FAX: +886-3-599-9176 E-mail: sales@chilisin.com http://www.chillisin.com		Chilis No. 7 Qingo TEL : FAX :	奇力新電子(東雲 in Electronics (Don 8, Puxing Rd., Yulia i Town, Dongguan +86-769-8773-025 : +86-769-8773-02 il:cect@chilisin.co	gguan) Co., Ltd. angwei Administration Area, City, Guangdong,China 51~3 32				
奇力新電子(越南廠)有限公 Chillisin Electronics (Vietnam) Lin No 143 - 145, Road No 10, VSIP Lap Le Commune, Thuy Nguyen Haiphong City, Vietnam Tel: 84-316 255 688 Fax: 84-3 E-mail: sales@chilisin.com	ited No. 8, Shaziao Liangshuijing Town, Yuanling County, Hai Phong, Dist, Tel: 86-745-867-5882							
			<u> </u>					
Drawn by 紅葉 Chang Yuwen	混 红	Checked	•	Approved 鍾瑞早 Jacky				

- 1 Scope: This specification applies to Alloy Molding power inductors
- 2 Part Numbering:



3 Rating:

Operating Temperature: $-40 \,^{\circ}\text{C} \sim 125 \,^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: - 4 0 °C ~ 1 2 5 °C(after PCB)

- $5 ^{\circ}\text{C} \sim 3 5 ^{\circ}\text{C}$, Humidity $4 5 \% \sim 8 5 \%$ (before PCB)

4 Marking:

No Marking

5 Standard Testing Condition

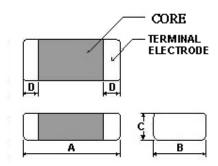
	In case of doubt	
Temperature	Ordinary Temperature(15 to 35℃)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



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EHEI252010A Series Specification

6 Configuration and Dimensions:



Dimensions in mm

TYPE	EHEI252010A
А	2.5±0.3
В	2.0±0.3
С	1.0max
D	0.6±0.3

7 Electrical Characteristics:

Part No.	Inductance	Tolerance	Test Freq.	Irms(A)	Isat(A)	RDC(mΩ)	
	(uH)	(±%)		Max.(Typ)	Max.(Typ)	Max.(Typ)	
EHEI252010A-1R0M-08	1.00	20	2MHz,0.2V	4 0(4 4)	5.0(5.2)	34(28)	

NOTE:

^{1.} Operating temperature range $-40 \,^{\circ}\text{C} \sim 125 \,^{\circ}\text{C}$ (Including self - temperature rise)

^{2.}Isat for Inductance drop 30% from its value without current.

^{3.}Irms for a 40°C temperature rise from 25°C ambient.

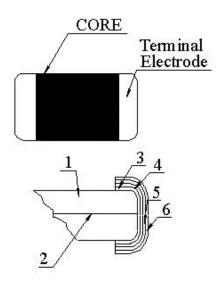
^{4.}Rated current: Isat or Irms, whichever is smaller

^{5.}All test data is referenced to 25°C ambient

^{6.}Absolute maximum voltage 20VDC



8 EHEI252010A Series 8.1 Construction:



8.2 Material List:

NO	Part	Description
1	Core	Metal Powder
2	Wire	Copper wire
3	Sputter/Plating	Cu
4	Silver Electrode	Ag
5	Plating	Ni
6	Plating	Sn

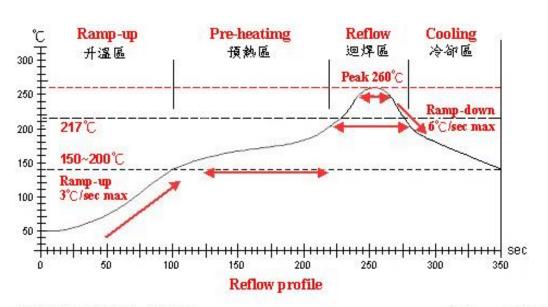


9 Reliability of molding power inductors 1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		metal body	Keeping Time: 30sec
1-1-2	Vibration	Appearance:No damage (for	Test device shall be soldered on the substrate
		microscope of CASTOR MZ-45 20X	Oscillation Frequency: 10 to 55 to 10Hz for 1min
		Inductance change shall be	Amplitude: 1.5mm
		within ±20%	Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5℃
		with solder.	Immersion Time: 10±1sec
		Inductance: within ±20% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°C
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		F F	Force : 5N
			Keeping Time: 10±1sec
		Mounting Pad	

No	Item	Specification		Test Method			
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:				
		Inductance:within±20% of	Step	Temperature (°ℂ)	Time (min)		
		initial value	1	-40±3	30		
			2	25±2	3		
			3	125±3	30		
			4	25±2	3		
			Total: 1000	cycles			
			Measured	after exposure in the room co	ndition for 24hrs		
1-2-2	Humidity Resistance	Resistance Temperature: 60±2°C					
			Relative H	umidity: 90 ~ 95% / Time: 500	hrs		
			Measured	after exposure in the room co	ndition for 24hrs		
1-2-3	High		Temperatu	re: 85±3℃			
	Temperature Resistance		Relative H	umidity: 0% / Time: 500hrs			
			Measured after exposure in the room condition				
1-2-4	Low		Temperature: -40±3°C				
	Temperature Resistance		Relative H	umidity: 0% / Time: 500hrs			
			Measured	after exposure in the room co	ndition for 24hrs		





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T. ~150°℃	150°C ~ 200°C	217℃	260±5°⊂	Peak Temp. ~ 150°C
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	k - 8
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	8 8

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



10 Packaging:

10.1 Packaging -Cover Tape

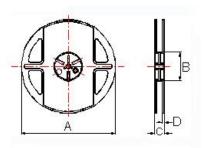
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



10.2 Packaging Quantity

TYPE	PCS/REEL		
EHEI252010A	3000		

10.3 Reel Dimensions



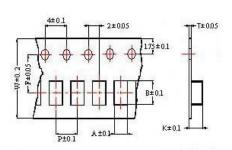
Dimensions in mm

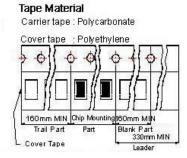
TYPE	А	В	С	D
EHEI252010A	178	60	12	1.5



10 Packaging:

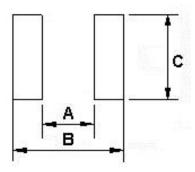
10.4 Tape Dimensions in mm





TYPE	Α	В	Т	W	Р	F	K
EHEI252010A	2.25	2.80	0.22	8	4	3.5	1.15

11 Recommended Land Pattern:



Dimensions in mm

TYPE	Α	В	С
EHEI252010A	1.2	2.8	2.3

12 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. After manufacturing process, there might be slight irregular shape on the edge of the products, and it's a normal phenomenon that can be neglectable.
- 6. The moisture sensitivity level (MSL) of products is classified as level 1.





